

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0878030152](#)  
**Status:** **Active**  
**Description:** 1.00mm (.039") Pitch DDR2 DIMM Socket, Through Hole, 25° Angle, 0.76µm (30µ") Gold (Au), 4.00mm (0.157") Solder tail, 240 Circuits, Lead free

**Documents:**

[3D Model](#) [Product Specification PS-87803-003 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**General**

Product Family	Memory Module Sockets
Series	87803
Comments	<LI>No Lubricant at the Contact <LI>Latches in Off-White Color
Component Type	Socket
JEDEC Outline	MO-237
Product Name	DDR2 DIMM

**Physical**

Circuits (Loaded)	240
Color - Resin	Black, Natural
Durability (mating cycles max)	25
Entry Angle	25° Angle
Keying to Mating Part	Yes
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
PC Tail Length (in)	0.157 In
PC Tail Length (mm)	4.00 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.125 In
PCB Thickness Recommended (mm)	3.18 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	100
Plating min: Termination (µm)	2.54
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole

**Electrical**

Current - Maximum per Contact	0.5A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	1.8V, Center

**Material Info**

**Reference - Drawing Numbers**

Product Specification	PS-87803-003
Sales Drawing	SD-87803-010

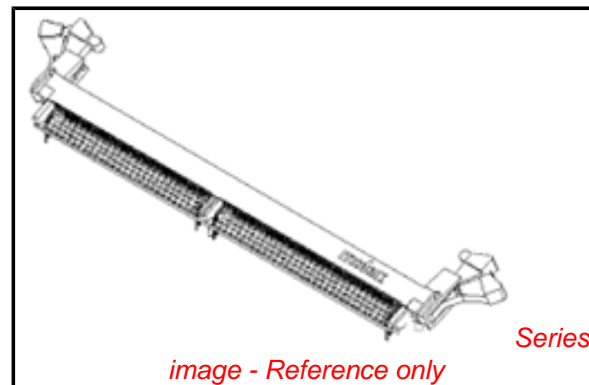


image - Reference only

Series

**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC Contains SVHC: No**  
**Halogen-Free Status**

**China RoHS**



**Not Reviewed**

**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

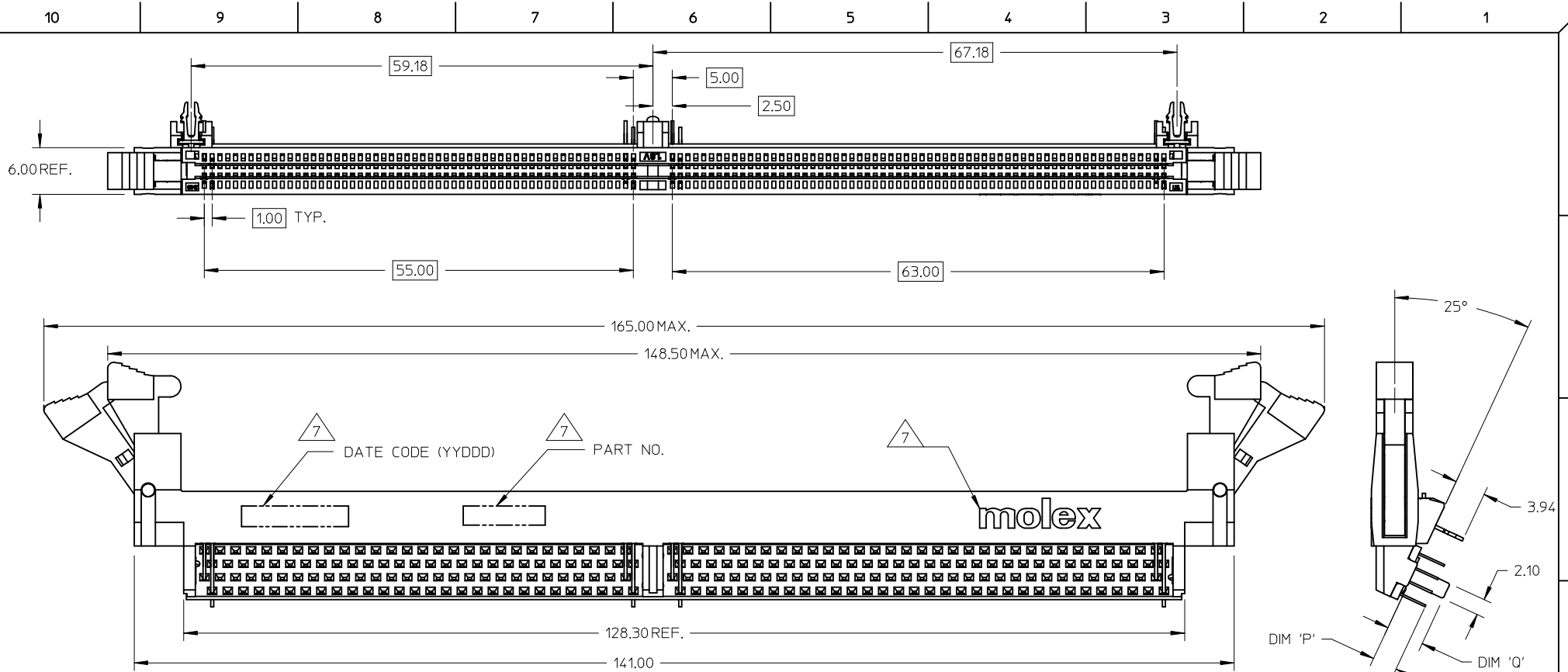
**Search Parts in this Series**

87803Series

**Mates With**

JEDEC standard 1.27mm modules

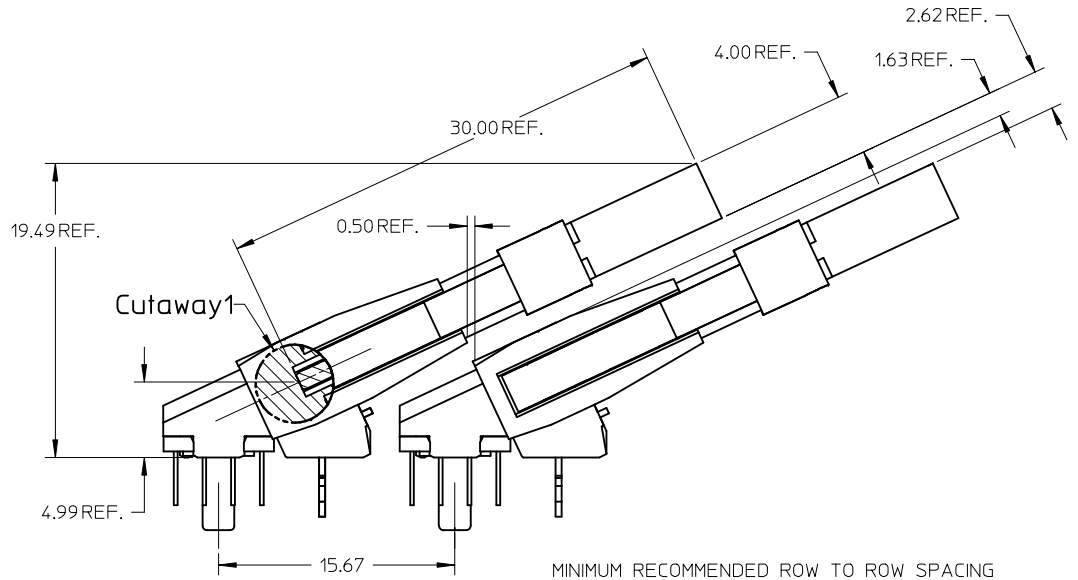
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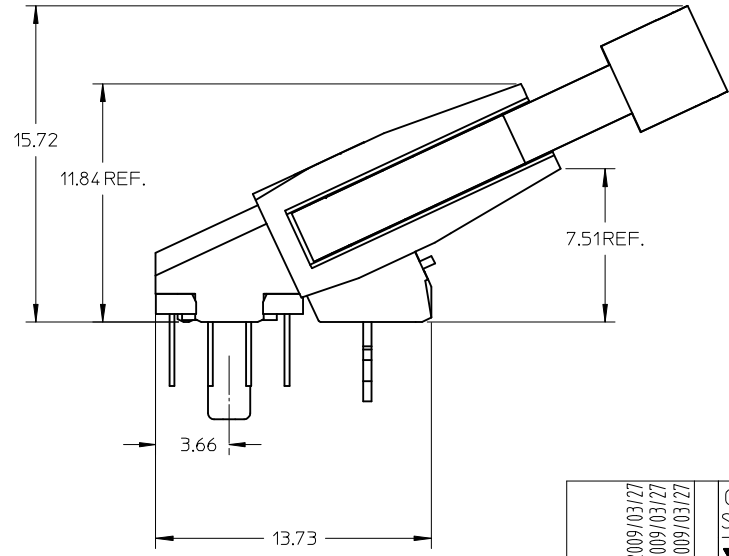
NOTES:

- MATERIALS : HOUSING AND BASEPLATE
  - LCP, GLASS FILLED, UL 94V-0, BLACK LATCH
  - HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
  - TERMINALS AND FORKLICK - COPPER ALLOY
- PLATING : CONTACT AREA - SEE TABLE IN SHEET 5  
SOLDERTAIL - SEE TABLE IN SHEET 5
- REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
- CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
- RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
- PRODUCT IS PACKED IN TRAY.
- MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
- CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

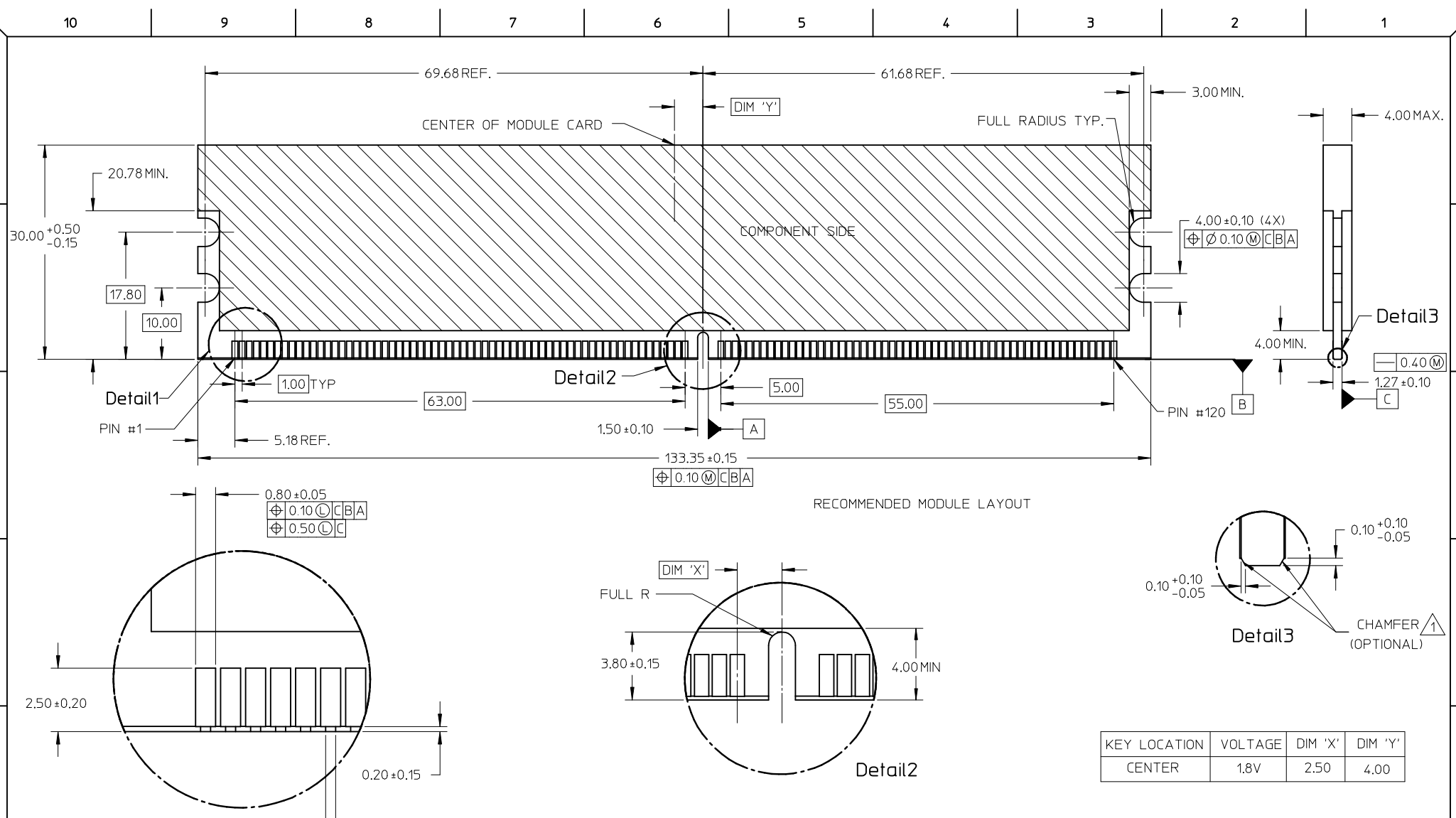
ADDED OPTION EC NO: S2009-0629 DRW: CCTEH 2009/03/27 CHKD: CGTAN 2009/03/27 APPR: SILENI 2009/03/27 B1	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		mm	INCH	MM ONLY	NTS	METRIC		
		4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
		3 PLACES	± ---	± ---	MLONG	2004/03/25	DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.	
			2 PLACES	± 0.25	± ---	CHECKED BY	DATE	
			1 PLACE	± ---	± ---	SRRAMESH	2004/03/26	
			ANGULAR ± 5 °		APPROVED BY	DATE		
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		GGLEE	2004/03/26		
			SEE TABLE		MATERIAL NO.	DOCUMENT NO.		
			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
					MOLEX MOLEX INCORPORATED		SHEET NO.	
					SD-87803-010		1 OF 5	



MINIMUM RECOMMENDED ROW TO ROW SPACING  
WHEN USING A 4.00MM THICK  
MODULE (TYPICAL TSOP PACKAGING)



ADDED OPTION EC NO: S2009-0629 DRWN: CCTEH 2009/03/27 CH'KD: GGTAN 2009/03/27 APPR: SHLENI 2009/03/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY	DATE	TITLE			
		4 PLACES	± ---	± ---	MLONG	2004/03/25	DDR2 DIMM, 1.00MM PITCH			
		3 PLACES	± ---	± ---	CHECKED BY	DATE	240 CKTS, 25 DEG.			
	2 PLACES	± 0.25	± ---	SRRAMESH	2004/03/26	MOLEX INCORPORATED				
	1 PLACE	± ---	± ---	APPROVED BY	DATE	DOCUMENT NO.				
	ANGULAR ± 5 °		GGLLEE		2004/03/26	SD-87803-010				
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		SEE TABLE	SHEET NO.				
			SIZE		A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

NOTES :  
 1 MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

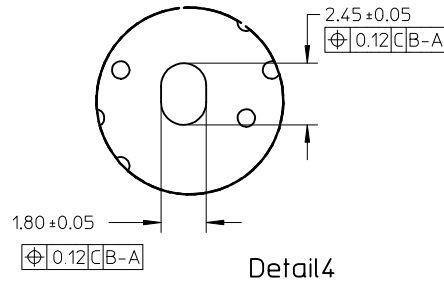
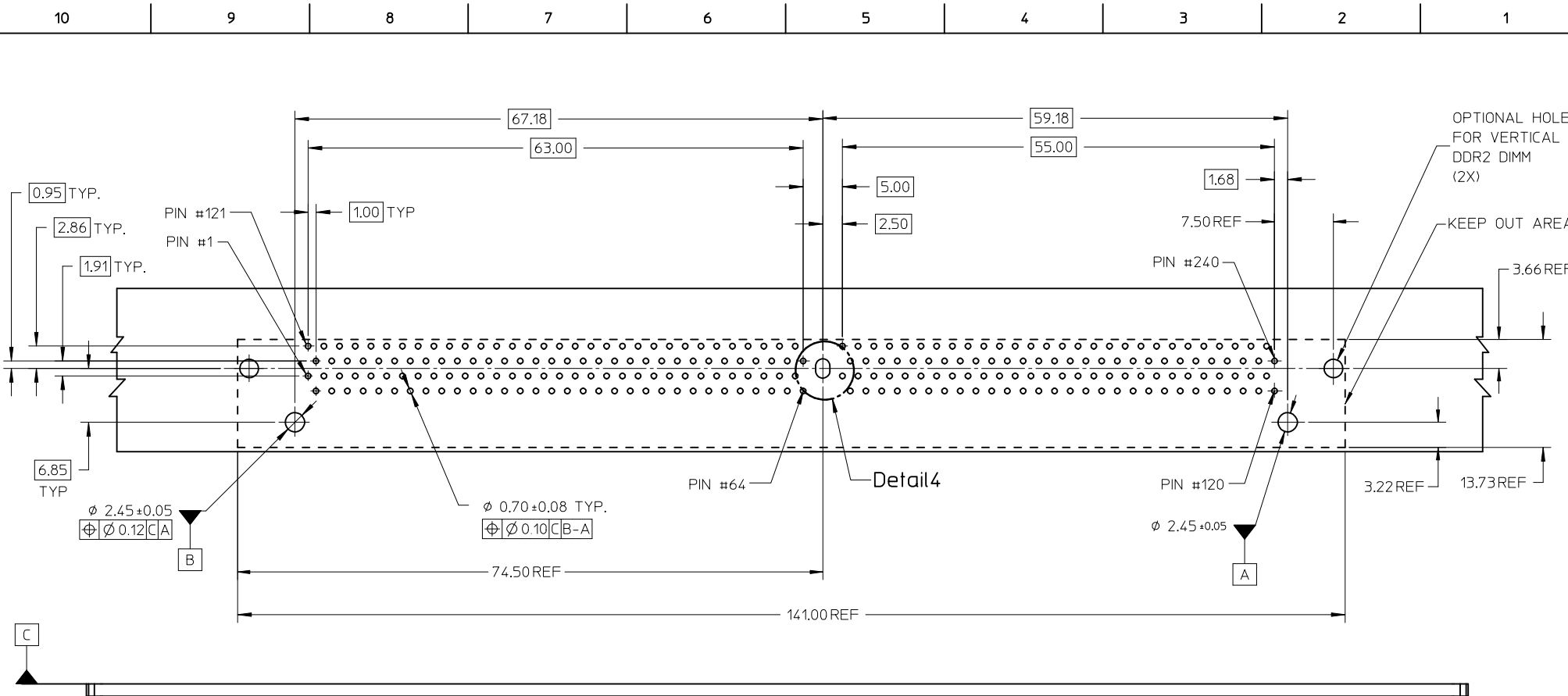
ADDED OPTION  
 EC NO: S2009-0629  
 DRW:NCCTEH  
 CHKD:CGTAN  
 APPR:SHLENI

REV	DESCRIPTION
B1	

QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
▽=0	4 PLACES ± ---	± ---
∇=0	3 PLACES ± ---	± ---
	2 PLACES ± 0.25	± ---
	1 PLACE ± ---	± ---
	ANGULAR ± 5 °	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
MLONG	2004/03/25
CHECKED BY	DATE
SRRAMESH	2004/03/26
APPROVED BY	DATE
GGLEE	2004/03/26
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	☉
TITLE		
DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
MOLEX INCORPORATED		SHEET NO.
DOCUMENT NO. SD-87803-010		3 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



<b>ADDED OPTION</b> EC NO: S2009-0629 DRWN: CCTEH CHKD: CGTAN APPR: SHLENI	2009/03/27 2009/03/27 2009/03/27	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>		SCALE <b>NTS</b>	DESIGN UNITS <b>METRIC</b>	THIRD ANGLE PROJECTION	
			4 PLACES ± --- ± ---	mm INCH	DRAWN BY MLONG	DATE 2004/03/25	TITLE <b>DDR2 DIMM, 1.00MM PITCH          240 CKTS, 25 DEG.</b>			
			3 PLACES ± --- ± ---		CHECKED BY SRRAMESH	DATE 2004/03/26	MOLEX INCORPORATED			
			2 PLACES ± 0.25 ± ---		APPROVED BY GGLEE	DATE 2004/03/26	MATERIAL NO. <b>SEE TABLE</b>	DOCUMENT NO. <b>SD-87803-010</b>	SHEET NO. <b>4 OF 5</b>	
1 PLACE ± --- ± ---		ANGULAR ± 5 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION
87803-0002	1.8V	2.79	3.18	1.57	0.38μM/ 15u" GOLD OVER 1.27μM/ 50u" MIN NICKEL	2.54μM/ 100u" MIN, TIN (MATTE) OVER 1.27μM/ 50u" MIN NICKEL	NO
87803-0022							YES
87803-0012		3.18	4.83	2.36			NO
87803-0032							YES
87803-0052		4.00	3.18	NO			
87803-0062				YES			
87803-0102		2.79	3.18	1.57	NO		
87803-0122					YES		
87803-0112		3.18	4.83	2.36	NO		
87803-0132					YES		
87803-0152			4.00	3.18	NO		
87803-0162					YES		

ADDED OPTION EC NO: S2009-0629 DRWN: CCTE CH'KD: GTAN APPR: SILENI 2009/03/27 2009/03/27 2009/03/27	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0 ◻=0	mm    INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± --- ± --- ANGULAR ± 5 °	MM ONLY	NTS	METRIC	DRAWN BY: MLONG    DATE: 2004/03/25 CHECKED BY: SRRAMESH    DATE: 2004/03/26 APPROVED BY: GGLEE    DATE: 2004/03/26	
	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE	TITLE: DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		MOLEX INCORPORATED	
	REV: B1			MATERIAL NO.	DOCUMENT NO.	SHEET NO.	

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